

LOGO MARK  
SEE NOTE 5.

DATUM PIN MARK  
SEE NOTES. 4

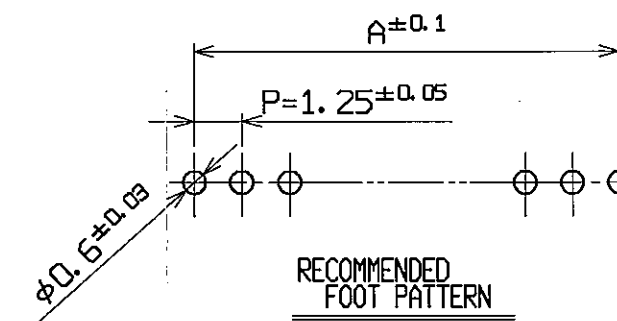
PART No.	POS.	A	B	C
20010-002-##	2	1.25	3.15	4.15
20010-003-##	3	2.5	4.4	5.4
20010-004-##	4	3.75	5.65	6.65
20010-005-##	5	5	6.9	7.9
20010-006-##	6	6.25	8.15	9.15
20010-007-##	7	7.5	9.4	10.4
20010-008-##	8	8.75	10.65	11.65
20010-009-##	9	10	11.9	12.9
20010-010-##	10	11.25	13.15	14.15
20010-011-##	11	12.5	14.4	15.4
20010-012-##	12	13.75	15.65	16.65
20010-013-##	13	15	16.9	17.9
20010-014-##	14	16.25	18.15	19.15
20010-015-##	15	17.5	19.4	20.4

☆EXAMPLE

20010-002 : WITH LOGO MARK  
20010-002-HO : WITHOUT LOGO MARK

NOTES.

- PIN RETENTION FORCE 1KgMIN.
- MATERIAL  
INSULATOR-PA, NATURAL (UL94V-0)  
PIN -COPPER ALLOY  
FINISH: Sn 2~3μm OVER  
Ni 0.6μmMIN. UNDERPLATE
- 20010-\*\*\*\*:SEE No. 300-012 OF THE PACKING STANDARD.  
20010-\*\*\*\*-HO:SEE No. 300-054 OF THE PACKING STANDARD.
- THIS MARK MEANS No. 1 POSITION.
- LOGO MARK INCLUDE THE INSC. BASE.



4	D6021	T. H	03/27/96	DESIGN' D BY	DATE	 Interconnect and Packaging Electronics TOKYO, JAPAN	TOL. ±0.3 ±2° TITLE DUALOK HEADER. S/T TMT			
3	D5058	T. H	11/06/95	T. HACHIYA	06/21/94					
2	D5001	T. H	03/06/95	CHK' D BY	DATE					
1	D4015	T. H	01/18/95	YIM	2/9/96					
0	D4008	T. H	11/25/94	APP' D BY	DATE					
5	D6092	T. T	08/02/96	REV. RECORD	8/30/96	SCALE	UNIT	DWG. No.	SHEET	REV.
REV	ECN	BY	DATE	SERIES No.	2210	5/1	MM	20010	1/1	5